Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT INFORMATION NOTIFICATION

PIN: PIN182410 **Date:** June 17, 2018

Subject: Qualification of Nitto EM-760L2 Die Attach Film for 48-Lead, Pb-Free, TSOP I Packages Assembled at OSE-Taiwan

To:

Change Type: Minor

Description of Change:
Cypress announces the qualification of Nitto EM-760L2 die attach film for 48-Lead, Pb-Free, TSOP I packages assembled at Orient Semiconductor Electronics, Taiwan (OSE-T). This product is RoHS and REACH compliant.

The 48-Lead, TSOP I, 12x18.4x1mm, Pb-Free packages are assembled at OSE-T using the following Bill of Materials:

Material	New OSE-T Bill of Materials	Current OSE-T Bill of Materials
Mold Compound	Hitachi CEL-9200HFU	Hitachi CEL-9200HFU
Leadfinish	Pure Sn	Pure Sn
Die Attach Film	Nitto EM-760L2	Nitto EM-700J
Bond Wire	0.9mil Au / 0.8mil CuPd	0.9mil Au / 0.8mil CuPd

There are no changes to ordering part numbers. Product datasheets remain the same and can be downloaded from the Cypress Website (www.cypress.com).

Benefit of Change:
This qualification is part of Cypress's continuous improvement in our flexible manufacturing initiative providing Cypress with the added capability to meet upside market demand, reduce business continuity risk, and ensure consistent and reliable delivery to customers in dynamic, changing market conditions.

Part Numbers Affected: 16
See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PIN will include all changes outlined in this PIN.

Qualification Status:
This change has been qualified through a series of tests documented in the Qualification Test Plan QTP#170502. This qualification report can be found as an attachment to this PIN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Approximate Implementation Date:
This change will be implemented effective with the date of this notification.

Anticipated Impact:
Products manufactured are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
This is an information only announcement. No response is required

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	Sample Order Part Number
1	CY14B116L-Z45XI	CY14B116L-Z45XIKO; subject to leadtime
2	CY14B116L-Z45XIT	CY14B116L-Z45XIKO; subject to leadtime
3	CY14B116N-Z30XI	CY14B116N-Z30XIKO; subject to leadtime
4	CY14B116N-Z30XIT	CY14B116N-Z30XIKO; subject to leadtime
5	CY14B116N-Z45XI	CY14B116N-Z45XIKO; subject to leadtime
6	CY14B116N-Z45XIT	CY14B116N-Z45XIKO; subject to leadtime
7	CY14E116N-Z30XI	CY14E116N-Z30XIKO; subject to leadtime
8	CY14E116N-Z30XIT	CY14E116N-Z30XIKO; subject to leadtime
9	CY62177ESL-55ZXI	CY62177ESL-55ZXIKO; subject to leadtime
10	CY62177ESL-55ZXIT	CY62177ESL-55ZXIKO; subject to leadtime
11	CY62177EV30LL-55ZXI	CY62177EV30LL-55ZXIKO
12	CY62177EV30LL-55ZXIT	CY62177EV30LL-55ZXIKO
13	CG7801AA	CG7801AAKO; subject to leadtime
14	CG7801AAT	CG7801AAKO; subject to leadtime
15	CG8210AA	CG8210AAKO; subject to leadtime
16	CG8210AAT	CG8210AAKO; subject to leadtime